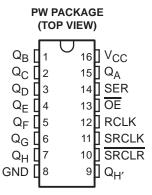
- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 7.4 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Supports Mixed-Mode Voltage Operation on All Ports
- 8-Bit Serial-In, Parallel-Out Shift
- I_{off} Supports Partial-Power-Down Mode Operation
- Shift Register Has Direct Clear



description/ordering information

The SN74LV595A is an 8-bit shift register designed for 2-V to 5.5-V V_{CC} operation.

This device contains an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. The storage register has parallel 3-state outputs. Separate clocks are provided for both the shift and storage register. The shift register has a direct overriding clear (\overline{SRCLR}) input, serial (\overline{SER}) input, and a serial output for cascading. When the output-enable (\overline{OE}) input is high, all outputs except $Q_{H'}$ are in the high-impedance state.

Both the shift register clock (SRCLK) and storage register clock (RCLK) are positive-edge triggered. If both clocks are connected together, the shift register always is one clock pulse ahead of the storage register.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

TA	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TSSOP - PW	Reel of 2000	SN74LV595AIPWREP	LV595EP

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



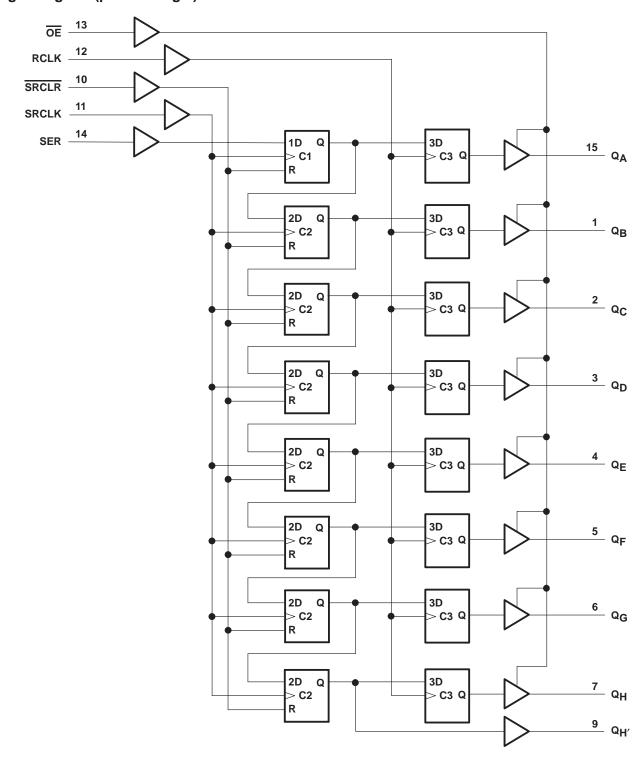
SN74LV595A-EP **8-BIT SHIFT REGISTER** WITH 3-STATE OUTPUT REGISTERS SCLS568B – JANUARY 2004 – REVISED MAY 2004

FUNCTION TABLE

		INPUTS			FUNCTION
SER	SRCLK	SRCLR	RCLK	OE	FUNCTION
Х	Х	Х	Х	Н	Outputs Q _A –Q _H are disabled.
Х	Χ	Χ	X	L	Outputs Q _A –Q _H are enabled.
Х	Χ	L	Χ	Χ	Shift register is cleared.
L	1	Н	Х	Х	First stage of the shift register goes low. Other stages store the data of previous stage, respectively.
Н	1	Н	Х	Х	First stage of the shift register goes high. Other stages store the data of previous stage, respectively.
Х	\downarrow	Н	Х	Χ	Shift-register state is not changed.
Х	Χ	X	\uparrow	Χ	Shift-register data is stored in the storage register.
Х	Χ	X	\downarrow	Χ	Storage-register state is not changed.

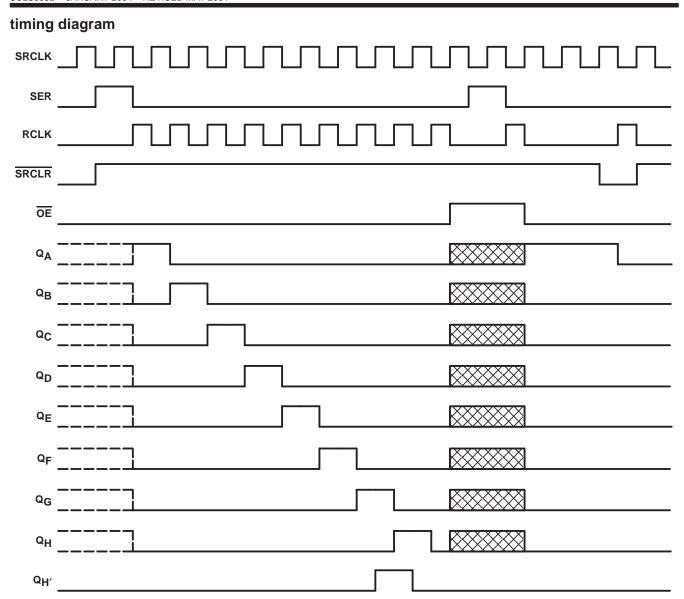


logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Output voltage range applied in the high or low state, V _O (see Notes 1 and 2)0.5	V to V_{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	–20 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 3)	108°C/W
Storage temperature range, T _{stg}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	V
		V _{CC} = 2 V	1.5		
.,	Heat I and Count and the ma	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} ×0.7		V
V_{IH}	High-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	V _{CC} ×0.7		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	V _{CC} ×0.7		
		V _{CC} = 2 V		0.5	
V/	Lauria de la controlta de	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$	V
V_{IL}	Low-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$		$V_{CC} \times 0.3$	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$V_{CC} \times 0.3$	
V_{I}	Input voltage		0	5.5	V
\/-	Output valtage	High or low state	0	VCC	V
VO	Output voltage	3-state	0	5.5	V
		V _{CC} = 2 V		-50	μΑ
1	High lavel autout august	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2	
ЮН	High-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-8	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-16	
		V _{CC} = 2 V		50	μΑ
	Lavorian et andre et anno et	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2	
lOL	Low-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		8	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		16	
		V _{CC} = 2.3 V to 2.7 V		200	
Δt/Δν	Input transition rise or fall rate	V _{CC} = 3 V to 3.6 V		100	ns/V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20	
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAR	AMETER	TEST CONDITIONS	v _{cc}	MIN	TYP	MAX	UNIT
		$I_{OH} = -50 \mu\text{A}$	2 V to 5.5 V	V _{CC} -0.1			
		$I_{OH} = -2 \text{ mA}$	2.3 V	2			
	$Q_{H'}$	I _{OH} = -6 mA	2.1/	2.48			V
VOH	Q _A -Q _H	IOH = -8 mA	3 V	2.48			V
	$Q_{H'}$	I _{OH} = -12 mA	4.5.1/	3.8			
	Q _A -Q _H	I _{OH} = -16 mA	4.5 V	3.8			
		I _{OL} = 50 μA	2 V to 5.5 V			0.1	
		$I_{OL} = 2 \text{ mA}$	2.3 V			0.4	
l.,	$Q_{H'}$	I _{OL} = 6 mA	0.1/			0.44	V
VOL	Q _A -Q _H	$I_{OL} = 8 \text{ mA}$	3 V			0.44	V
	$Q_{H'}$	I _{OL} = 12 mA	4.5.1/			0.55	
	Q _A -Q _H	I _{OL} = 16 mA	4.5 V			0.55	
II		V _I = 5.5 V or GND	0 to 5.5 V			±1	μΑ
loz		$V_O = V_{CC}$ or GND	5.5 V			±5	μΑ
ICC		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20	μΑ
I _{off}		V_I or $V_O = 0$ to 5.5 V	0			5	μΑ
Ci	_	$V_I = V_{CC}$ or GND	3.3 V		3.5		pF

timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

			T _A = 2	T _A = 25°C		MAY		
			MIN	MAX	MIN	MAX	UNIT	
t _W Pulse duration		SRCLK high or low	7		7.5			
	RCLK high or low	7		7.5		ns		
		SRCLR low	6		6.5			
		SER before SRCLK↑	5.5		5.5			
١.	Oats up time a	SRCLK↑ before RCLK↑†	8		9			
t _{su}	Setup time	SRCLR low before RCLK↑	8.5		9.5		ns	
		SRCLR high (inactive) before SRCLK↑	4		4			
th	Hold time	SER after SRCLK↑	1.5		1.5		ns	

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.



timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

				T _A = 25°C			MAY	
			MIN	MAX	MIN	MAX	UNIT	
		SRCLK high or low	5.5		5.5			
t _w	t _W Pulse duration	RCLK high or low	5.5		5.5		ns	
		SRCLR low	5		5			
		SER before SRCLK↑	3.5		3.5			
١.	Cohun time	SRCLK↑ before RCLK↑†	8		8.5		ns	
t _{su}	Setup time	SRCLR low before RCLK↑	8		9			
		SRCLR high (inactive) before SRCLK↑	3		3			
t _h	Hold time	SER after SRCLK↑	1.5		1.5		ns	

This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			$T_A = 2$	25°C		MAY	
			MIN	MAX	MIN	MAX	UNIT
		SRCLK high or low	5		5		
t _W	t _W Pulse duration	RCLK high or low	5		5		ns
		SRCLR low	5.2		5.2		
		SER before SRCLK↑	3		3		
١.	Catur time	SRCLK↑ before RCLK↑†	5		5		
tsu	Setup time	SRCLR low before RCLK↑	5		5		ns
		SRCLR high (inactive) before SRCLK↑	2.5		2.5		
th	Hold time	SER after SRCLK↑	2		2		ns

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	T,	գ = 25°C	;		MAY	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
,			C _L = 15 pF	65	80		45		N 41 1-
f _{max}			C _L = 50 pF	60	70		40		MHz
^t PLH	DOLK	0 0			8.4	14.2	1	15.8	
^t PHL	RCLK Q _A -Q _H]		8.4	14.2	1	15.8		
^t PLH	CDCLIA				9.4	19.6	1	22.2	
^t PHL	SRCLK	Q _H ′]		9.4	19.6	1	22.2	
^t PHL	SRCLR	$Q_{H'}$	C _L = 15 pF		8.7	14.6	1	16.3	ns
^t PZH	ŌĒ	ŌĒ Q _A −Q _H]		8.2	13.9	1	15	
tPZL					10.9	18.1	1	20.3	
^t PHZ]		8.3	13.7	1	15.6	
^t PLZ	ŌĒ	Q _A –Q _H			9.2	15.2	1	16.7	
^t PLH	DOLK	0.0			11.2	17.2	1	19.3	
^t PHL	RCLK	Q_A-Q_H]		11.2	17.2	1	19.3	
^t PLH	CDCLIA	0			13.1	22.5	1	25.5	
^t PHL	SRCLK	Q _H ′]		13.1	22.5	1	25.5	
^t PHL	SRCLR	Q _H ′	$C_{L} = 50 \text{ pF}$		12.4	18.8	1	21.1	ns
^t PZH			1		10.8	17	1	18.3	
[†] PZL	ŌE ŌE	Q _A –Q _H			13.4	21	1	23	
^t PHZ		0.0	1		12.2	18.3	1	19.5	
^t PLZ	ÜE	Q _A –Q _H			14	20.9	1	22.6	



SN74LV595A-EP **8-BIT SHIFT REGISTER** WITH 3-STATE OUTPUT REGISTERS SCLS568B - JANUARY 2004 - REVISED MAY 2004

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	T,	4 = 25°C	;	MIN	BAAV	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
			C _L = 15 pF	80	120		70		N 41 1-
f _{max}			C _L = 50 pF	55	105		50		MHz
^t PLH	DOLK				6	11.9	1	13.5	
^t PHL	RCLK	Q_A-Q_H			6	11.9	1	13.5	
^t PLH	CDCLK				6.6	13	1	15	
^t PHL	SRCLK	Q _H ′			6.6	13	1	15	
^t PHL	SRCLR	Q _H ′	C _L = 15 pF		6.2	12.8	1	13.7	ns
^t PZH		0.00			6	11.5	1	13.5	
^t PZL	ŌĒ	Q_A-Q_H			7.8	11.5	1	13.5	
^t PHZ	ŌĒ				6.1	14.7	1	15.2	
tPLZ	OE	Q_A-Q_H			6.3	14.7	1	15.2	
^t PLH	DOLK	0 0			7.9	15.4	1	17	
^t PHL	RCLK	Q_A-Q_H			7.9	15.4	1	17	
^t PLH	CDCLK	0			9.2	16.5	1	18.5	
^t PHL	SRCLK	Q _H ′			9.2	16.5	1	18.5	
^t PHL	SRCLR	Q _H ′	C _L = 50 pF		9	16.3	1	17.2	ns
^t PZH			7		7.8	15	1	17	
^t PZL	ŌĒ	Q_A-Q_H			9.6	15	1	17	
^t PHZ		0 . 0	7		8.1	15.7	1	16.2	
^t PLZ	ŌĒ	Q _A –Q _H			9.3	15.7	1	16.2	

SCLS568B - JANUARY 2004 - REVISED MAY 2004

switching characteristics over recommended operating free-air temperature range, $V_{\hbox{CC}}$ = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	Վ = 25° C	;	B.A.I.N.I	14 A V	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
			C _L = 15 pF	135	170		115		N 41 1-
f _{max}			C _L = 50 pF	120	140		95		MHz
tPLH	BOLK	0 0			4.3	7.4	1	8.5	
^t PHL	RCLK	Q_A-Q_H			4.3	7.4	1	8.5	
t _{PLH}	CDCI IX	•			4.5	8.2	1	9.4	
^t PHL	SRCLK	Q _H ′			4.5	8.2	1	9.4	
^t PHL	SRCLR	Q _H ′	C _L = 15 pF		4.5	8	1	9.1	ns
^t PZH	ŌĒ ŌĒ	Q _A -Q _H]		4.3	8.6	1	10	
tpZL					5.4	8.6	1	10	
^t PHZ		0.00			2.4	6	1	7.1	
tPLZ	OE	Q_A – Q_H			2.7	5.1	1	7.2	
^t PLH	RCLK	0 . 0			5.6	9.4	1	10.5	
^t PHL	ROLK	Q_A-Q_H			5.6	9.4	1	10.5	
^t PLH	SRCLK	0			6.4	10.2	1	11.4	
^t PHL	SRULK	Q _H ′			6.4	10.2	1	11.4	
^t PHL	SRCLR	$Q_{H'}$	$C_{L} = 50 \text{ pF}$		6.4	10	1	11.1	ns
^t PZH	OE Q _A -Q _H]		5.7	10.6	1	12	
tpZL		QA-QH]		6.8	10.6	1	12	
^t PHZ		0.0.	0.0.	7		3.5	10.3	1	11
tPLZ	OE	Q _A -Q _H			3.4	10.3	1	11	

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.3		V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.2		V
VOH(V)	Quiet output, minimum dynamic VOH		2.8		V
V _{IH} (D)	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

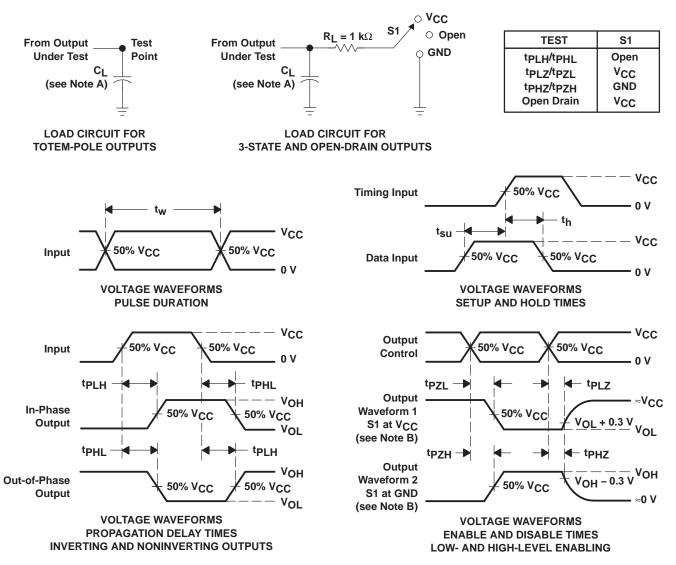
NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER			TEST CONDITIONS			UNIT
C _{pd}	Power dissipation capacitance	C _L = 50 pF,	f = 10 MHz	3.3 V	111	pF
				5 V	114	



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzi and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins P	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV595AIPWREP	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04696-01XE	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LV595A-EP:

Catalog: SN74LV595A

Automotive: SN74LV595A-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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